

**REWORKABLE AND THERMALLY
CONDUCTIVE ADHESIVE AND USE THEREOF**

ABSTRACT OF DISCLOSURE

5

Reworkable thermally conductive adhesive composition comprising a cured reaction product from a diepoxide wherein the epoxy groups are connected through an acyclic acetal moiety, a cyclic anhydride and a thermally conductive filler are provided and used to bond semiconductive devices to a chip carrier or heat spreader.